

MPM ACCUFLEX SOLDER PRINTER

SPECIFICATIONS

Board Handling	Maximum circuit board dimension	584×508mm
	Minimum circuit board dimension	75×50mm
	Circuit board thickness	0.8~5.0
	Maximum circuit board weight	4.5kg
	Minimum circuit board edge surface clearance	5mm
	Maximum upper clearance	15mm
	Transfer speed	Adjustable
	Transfer height from the bottom	860~960mm
	Circuit board retention	Clamping circuit (front & back of the circuit)
Circuit board support	Standalone mobile magnetic support pin	
Printing Parameters	Maximum printing area	559×498mm
	Snap off speed	0.2~10mm / sec
	Printing speed	5~200mm / sec
	Printing pressure	Less than 20kg
	Print stroke	508mm
	Stencil frame size	737×737mm(standard)
	Applied compact frame	Optional adapter used
Vision	Scope of vision	10×10mm
	Recognition marks	Standard shape marks, Refer to SMEMA standard
	Camera system	A unit of mobile camera with two beams
Performance	Alignment reproducibility	±0.025mm@6sigma(Cp should be 2.0 or more) Already verified by the glass plate capability test
	Cycle time / Standard spec. machine	16.2 sec. (printing time excluded)
	Cycle time / High speed spec. machine	11 sec. (printing time excluded)
	Circuit board retention	Clamping circuit (front & back of the circuit board)
	Power source etc.	
Power source	110 ~ 240V、 50/60HZ (±10%)	
Air	0.63Mpa SCFM clean air	
High	1575mm	
Depth	1448mm	
Width(standard spec.)	1314mm	
Width(high speed spec.)	1320mm、 1524mm、 1727mm	
Device weight	700kg	
Packing weight	1140kg	